AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (Previously Presented) A flexible metal-clad laminate comprising a metal foil and a heat-resistant resin film layer formed on one side of the metal foil, produced by applying a solution containing an organic solvent and a condensation polymer to the metal foil and drying the laminate, the heat-resistant resin film layer comprising a crosslinked condensation polymer and having an N-methyl-2-pyrrolidone-insoluble content of at least 1%, wherein

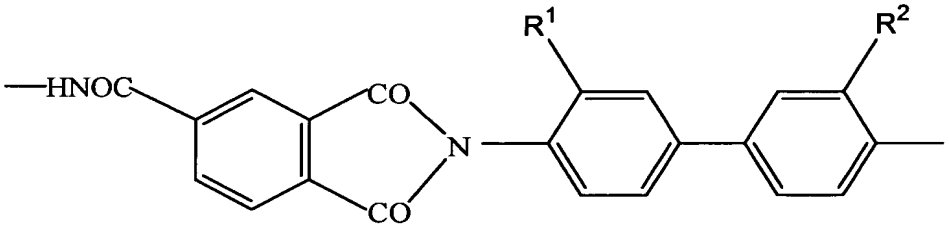
the flexible metal-clad laminate has a radius of curvature of at least 15 cm,

the heat-resistant resin film layer has a thermal gradient dimensional change of not more than 0.1% when heated at 200 °C for 30 minutes,

the average surface roughness Ra of the surface of the heat-resistant resin film layer which is in contact with the metal foil is not more than 0.4 μm,

the thickness of the metal foil is from 3 to 50 μm, and

the condensation polymer comprises the unit represented by formula (1)



(1)

wherein R^1 and R^2 are the same and each represents a methyl group.

2. (Original) The flexible metal-clad laminate according to claim 1, wherein the heat resistant resin film layer is formed by converting an organic solvent-soluble condensation polymer by crosslinking into an organic solvent-insoluble form.

3. (Original) The flexible metal-clad laminate according to claim 1, wherein the heat-resistant resin film layer is formed by applying to the metal foil a solution prepared by dissolving an organic solvent-soluble condensation polymer in the organic solvent and

subjecting the coated metal foil to a predrying step, and a heat-treatment and solvent removal step.

4. (Original) The flexible metal-clad laminate according to claim 1, wherein the heat-resistant resin film layer has an initiation tear strength (film thickness: 20 μm) of at least 15 kg and has a thermal gradient dimensional change of not more than 0.1% when heated at 200°C for 30 minutes.

5. (Original) The flexible metal-clad laminate according to claim 1, which has a solder heat resistance of at least 350°C, an adhesion between the metal foil and the heat-resistant resin film of at least 80 g/mm and a radius of curvature of at least 15 cm..

6. (Cancelled)

7. (Original) The flexible metal-clad laminate according to claim 1, wherein the elastic modulus retentivity of the heat-resistant resin film after being immersed in an aqueous solution of sodium hydroxide (40% by weight) at 25°C for 100 hours is at least 40%.

8.-17. (Cancelled)

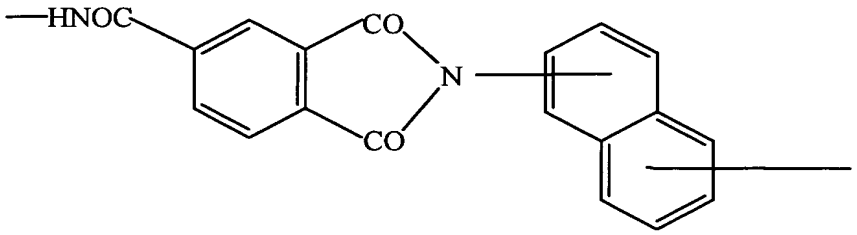
18. (Previously Presented) A flexible printed wiring board comprising the flexible metal-clad laminate according to claim 1.

19. (Currently Amended) A flexible metal-clad laminate comprising a metal foil and a heat-resistant resin film layer formed on one side of the metal foil, produced by applying a solution containing an organic solvent and a condensation polymer to the metal foil and drying the laminate, the heat-resistant resin film layer comprising a crosslinked condensation polymer and having an N-methyl-2-pyrrolidone-insoluble content of at least 1%, wherein

the average surface roughness Ra of the surface of the heat-resistant resin film layer which is in contact with the metal foil is not more than 0.4 μm,

the thickness of the metal foil is from 3 to 50 μm, and

the condensation polymer comprises the unit represented by formula (2)



(2) .

20. (Previously Presented) The flexible metal-clad laminate according to claim 19, wherein the heat resistant resin film layer is formed by converting an organic solvent-soluble condensation polymer by crosslinking into an organic solvent-insoluble form.

21. (Previously Presented) The flexible metal-clad laminate according to claim 19, wherein the heat-resistant resin film layer is formed by applying to the metal foil a solution prepared by dissolving an organic solvent-soluble condensation polymer in the organic solvent and subjecting the coated metal foil to a predrying step and a heat-treatment and solvent removal step.

22. (Previously Presented) The flexible metal-clad laminate according to claim 19, wherein the heat-resistant resin film layer has an initiation tear strength (film thickness: 20 μm) of at least 15 kg and has a thermal gradient dimensional change of not more than 0.1% when heated at 200 °C for 30 minutes.

23. (Previously Presented) The flexible metal-clad laminate according to claim 19, which has a solder heat resistance of at least 350 °C, an adhesion between the metal foil and the heat-resistant resin film of at least 80 g/mm, and a radius of curvature of at least 15 cm.

24. (Previously Presented) The flexible metal-clad laminate according to claim 19, wherein the average surface roughness of the surface of the heat-resistant resin film layer which is in contact with the metal foil is not more than 0.4 μm.

25. (Previously Presented) The flexible metal-clad laminate according to claim 19, wherein the elastic modulus retentivity of the heat-resistant resin film after being

immersed in an aqueous solution of sodium hydroxide (40% by weight) at 25 °C for 100 hours is at least 40%.

26. (Previously Presented) A flexible printed wiring board comprising the flexible metal-clad laminate according to claim 19.